



## **Ferrites and accessories**

ETD 29/16/10

Core and accessories

**Series/Type:**            **B66358, B66359**

**Date:**                    **October 2022**

ETD 29/16/10

Core

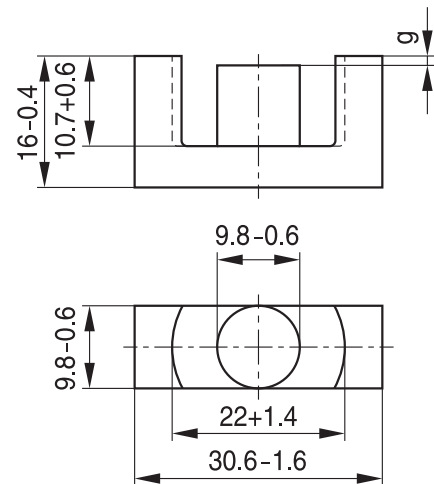
B66358

- To IEC 63093-6
- For SMPS transformers with optimum weight/performance ratio at small volume
- Delivery mode: single units

**Magnetic characteristics (per set)**

$\Sigma l/A = 0.93 \text{ mm}^{-1}$   
 $l_e = 70.4 \text{ mm}$   
 $A_e = 76.0 \text{ mm}^2$   
 $A_{\min} = 71.0 \text{ mm}^2$   
 $V_e = 5350 \text{ mm}^3$

**Approx. weight 28 g/set**



FEK0765-U

**Ungapped**

Material	$A_L$ value nH	$\mu_e$	$P_V$ W/set	Ordering code
N27	2000 +30/-20%	1470	< 1.04 (200 mT, 25 kHz, 100 °C)	B66358G0000X127
N87	2200 +30/-20%	1610	< 2.80 (200 mT, 100 kHz, 100 °C)	B66358G0000X187
N97	2250 +30/-20%	1670	< 2.40 (200 mT, 100 kHz, 100 °C)	B66358G0000X197

**Gapped ( $A_L$  values/air gaps examples)**

Material	g mm	$A_L$ value approx. nH	$\mu_e$	Ordering code ** = 27 (N27) = 87 (N87)
N27,	0.10 ±0.02	621	457	B66358G0100X1**
N87	0.20 ±0.02	383	281	B66358G0200X1**
	0.50 ±0.05	201	148	B66358G0500X1**
	1.00 ±0.05	124	91	B66358G1000X1**

The  $A_L$  value in the table applies to a core set comprising one ungapped core (dimension g = 0 mm) and one gapped core (dimension g > 0 mm).

Other  $A_L$  values/air gaps and materials available on request — see Processing remarks on page 6.

ETD 29/16/10

Core

B66358

**Calculation factors** (for formulas, see “*E cores: general information*”)

Material	Relationship between air gap – $A_L$ value		Calculation of saturation current			
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)
N27	124	-0.7	195	-0.847	181	-0.865
N87	124	-0.7	192	-0.796	176	-0.873

Validity range:      K1, K2: 0.10 mm < s < 2.00 mm  
                              K3, K4: 70 nH <  $A_L$  < 680 nH

**Coil former** (magnetic axis horizontal)

Material: GFR polyterephthalate, UL 94 V-0, insulation class to IEC 60085:  
 B66359B: F  $\triangleq$  max. operating temperature 155 °C, color code black  
 Valox 420-SE0 [E207780 (M)] SABIC JAPAN L L C  
 B66359W: H  $\triangleq$  max. operating temperature 180 °C, color code black  
 Rynite FR 530® [E41938 (M)], E I DUPONT DE NEMOURS & CO INC

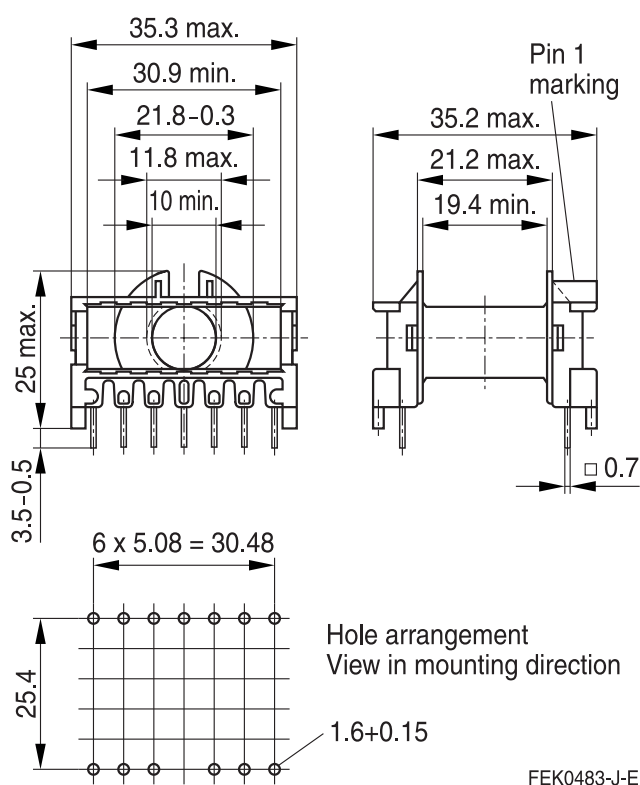
Solderability: to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s  
 Resistance to soldering heat: to IEC 60068-2-20, test Tb, method 1B: 350 °C, 3.5 s  
 Winding: see Processing notes, 2.1  
 Pins: Squared pins

**Yoke**

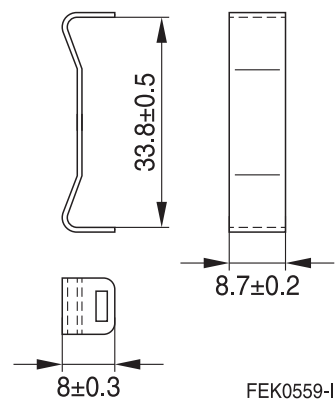
Material: Stainless spring steel (0.3 mm)

Coil former					Ordering code
Sections	A <sub>N</sub> mm <sup>2</sup>	l <sub>N</sub> mm	A <sub>R</sub> value μΩ	Pins	
1	97	52.8	18.7	13	B66359B1013T001 B66359W1013T001
Yoke (ordering code per piece, 2 are required)					B66359S2000X000

**Coil former**



**Yoke**



**Coil former (magnetic axis vertical)**

Material: GFR polyterephthalate (UL 94 V-0, insulation class to IEC 60085:  
H  $\geq$  max. operating temperature 180 °C), color code black  
Rynite FR 530® [E41938 (M)], E I DUPONT DE NEMOURS & CO INC

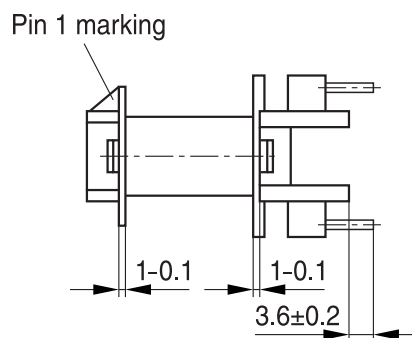
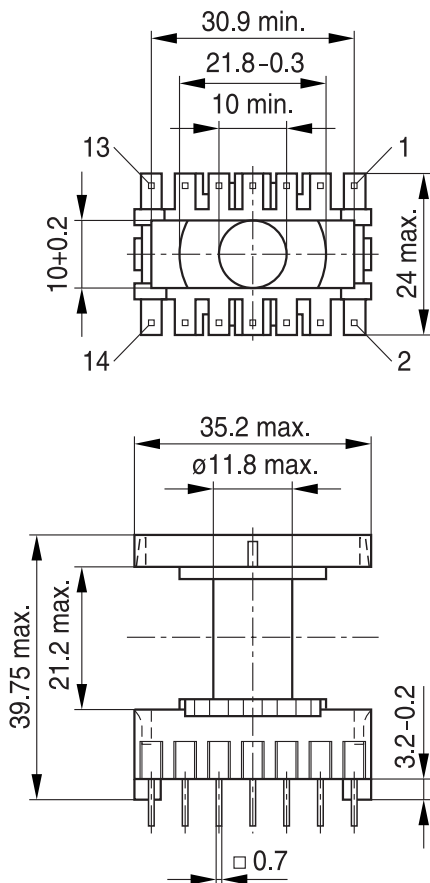
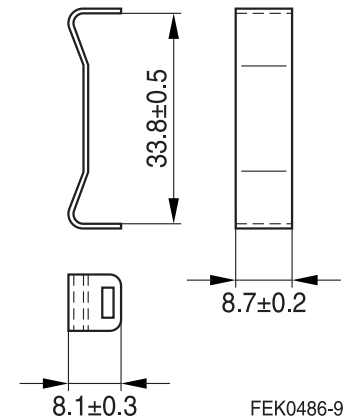
Solderability: to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s  
Resistance to soldering heat: to IEC 60068-2-20, test Tb, method 1B: 350 °C, 3.5 s

Winding: see Processing notes, 2.1  
Pins: Squared pins

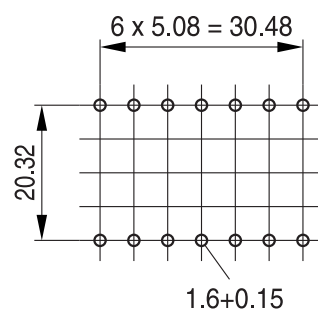
**Yoke**

Material: Stainless spring steel (0.3 mm)

Coil former					Ordering code
Sections	A <sub>N</sub> mm <sup>2</sup>	l <sub>N</sub> mm	A <sub>R</sub> value μΩ	Pins	
1	97	52.8	18.7	14	B66359X1014T001
Yoke (ordering code per piece, 2 are required)					B66359S2000X000

**Coil former**

**Yoke**


Hole arrangement  
View in mounting direction



FEK0485-1-E

## Ferrites and accessories

### Cautions and warnings

#### Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter “*General - Definitions, 8.1*”.

#### Effects of core combination on $A_L$ value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter “*General - Definitions, 8.1*”.

#### Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

#### NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

#### Ferrite Accessories

Our ferrite accessories have been designed and evaluated only in combination with our ferrite cores. We explicitly point out that our ferrite accessories or our ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

We assume no warranty or reliability for the combination of our ferrite accessories with cores and other accessories from any other manufacturer.

#### Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter “*Processing notes*”, section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.

**Display of ordering codes for TDK Electronics products**

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## Ferrites and accessories

### Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm <sup>2</sup>
A <sub>e</sub>	Effective magnetic cross section	mm <sup>2</sup>
A <sub>L</sub>	Inductance factor; $A_L = L/N^2$	nH
A <sub>L1</sub>	Minimum inductance at defined high saturation ( $\cong \mu_a$ )	nH
A <sub>min</sub>	Minimum core cross section	mm <sup>2</sup>
A <sub>N</sub>	Winding cross section	mm <sup>2</sup>
A <sub>R</sub>	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega = 10^{-6} \Omega$
B	RMS value of magnetic flux density	Vs/m <sup>2</sup> , mT
$\Delta B$	Flux density deviation	Vs/m <sup>2</sup> , mT
$\hat{B}$	Peak value of magnetic flux density	Vs/m <sup>2</sup> , mT
$\Delta \hat{B}$	Peak value of flux density deviation	Vs/m <sup>2</sup> , mT
B <sub>DC</sub>	DC magnetic flux density	Vs/m <sup>2</sup> , mT
B <sub>R</sub>	Remanent flux density	Vs/m <sup>2</sup> , mT
B <sub>S</sub>	Saturation magnetization	Vs/m <sup>2</sup> , mT
C <sub>0</sub>	Winding capacitance	F = As/V
CDF	Core distortion factor	mm <sup>-4.5</sup>
DF	Relative disaccommodation coefficient $DF = d/\mu_i$	
d	Disaccommodation coefficient	
E <sub>a</sub>	Activation energy	J
f	Frequency	s <sup>-1</sup> , Hz
f <sub>cutoff</sub>	Cut-off frequency	s <sup>-1</sup> , Hz
f <sub>max</sub>	Upper frequency limit	s <sup>-1</sup> , Hz
f <sub>min</sub>	Lower frequency limit	s <sup>-1</sup> , Hz
f <sub>r</sub>	Resonance frequency	s <sup>-1</sup> , Hz
f <sub>Cu</sub>	Copper filling factor	
g	Air gap	mm
H	RMS value of magnetic field strength	A/m
$\hat{H}$	Peak value of magnetic field strength	A/m
H <sub>DC</sub>	DC field strength	A/m
H <sub>c</sub>	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 <sup>-6</sup> cm/A
h/ $\mu_i^2$	Relative hysteresis coefficient	10 <sup>-6</sup> cm/A
I	RMS value of current	A
I <sub>DC</sub>	Direct current	A
$\hat{I}$	Peak value of current	A
J	Polarization	Vs/m <sup>2</sup>
k	Boltzmann constant	J/K
k <sub>3</sub>	Third harmonic distortion	
k <sub>3c</sub>	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



**Ferrites and accessories**
**Symbols and terms**

Symbol	Meaning	Unit
$\Delta L/L$	Relative inductance change	H
$L_0$	Inductance of coil without core	H
$L_H$	Main inductance	H
$L_p$	Parallel inductance	H
$L_{rev}$	Reversible inductance	H
$L_s$	Series inductance	H
$l_e$	Effective magnetic path length	mm
$l_N$	Average length of turn	mm
$N$	Number of turns	
$P_{Cu}$	Copper (winding) losses	W
$P_{trans}$	Transferrable power	W
$P_V$	Relative core losses	mW/g
PF	Performance factor	
$Q$	Quality factor ( $Q = \omega L/R_s = 1/\tan \delta_L$ )	
$R$	Resistance	$\Omega$
$R_{Cu}$	Copper (winding) resistance ( $f = 0$ )	$\Omega$
$R_h$	Hysteresis loss resistance of a core	$\Omega$
$\Delta R_h$	$R_h$ change	$\Omega$
$R_i$	Internal resistance	$\Omega$
$R_p$	Parallel loss resistance of a core	$\Omega$
$R_s$	Series loss resistance of a core	$\Omega$
$R_{th}$	Thermal resistance	K/W
$R_V$	Effective loss resistance of a core	$\Omega$
$s$	Total air gap	mm
$T$	Temperature	$^{\circ}\text{C}$
$\Delta T$	Temperature difference	K
$T_C$	Curie temperature	$^{\circ}\text{C}$
$t$	Time	s
$t_v$	Pulse duty factor	
$\tan \delta$	Loss factor	
$\tan \delta_L$	Loss factor of coil	
$\tan \delta_r$	(Residual) loss factor at $H \rightarrow 0$	
$\tan \delta_e$	Relative loss factor	
$\tan \delta_h$	Hysteresis loss factor	
$\tan \delta/\mu_i$	Relative loss factor of material at $H \rightarrow 0$	
$U$	RMS value of voltage	V
$\hat{U}$	Peak value of voltage	V
$V_e$	Effective magnetic volume	$\text{mm}^3$
$Z$	Complex impedance	$\Omega$
$Z_n$	Normalized impedance $ Z _n =  Z /N^2 \times \varepsilon (l_e/A_e)$	$\Omega/\text{mm}$

## Ferrites and accessories

### Symbols and terms

Symbol	Meaning	Unit
$\alpha$	Temperature coefficient (TK)	1/K
$\alpha_F$	Relative temperature coefficient of material	1/K
$\alpha_e$	Temperature coefficient of effective permeability	1/K
$\epsilon_r$	Relative permittivity	
$\Phi$	Magnetic flux	Vs
$\eta$	Efficiency of a transformer	
$\eta_B$	Hysteresis material constant	mT <sup>-1</sup>
$\eta_i$	Hysteresis core constant	A <sup>-1</sup> H <sup>-1/2</sup>
$\lambda_s$	Magnetostriction at saturation magnetization	
$\mu$	Relative complex permeability	
$\mu_0$	Magnetic field constant	Vs/Am
$\mu_a$	Relative amplitude permeability	
$\mu_{app}$	Relative apparent permeability	
$\mu_e$	Relative effective permeability	
$\mu_i$	Relative initial permeability	
$\mu_p'$	Relative real (inductive) component of $\bar{\mu}$ (for parallel components)	
$\mu_p''$	Relative imaginary (loss) component of $\bar{\mu}$ (for parallel components)	
$\mu_r$	Relative permeability	
$\mu_{rev}$	Relative reversible permeability	
$\mu_s'$	Relative real (inductive) component of $\bar{\mu}$ (for series components)	
$\mu_s''$	Relative imaginary (loss) component of $\bar{\mu}$ (for series components)	
$\mu_{tot}$	Relative total permeability derived from the static magnetization curve	
$\rho$	Resistivity	$\Omega\text{m}^{-1}$
$\Sigma l/A$	Magnetic form factor	mm <sup>-1</sup>
$\tau_{Cu}$	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	s
$\omega$	Angular frequency; $\omega = 2 \pi f$	s <sup>-1</sup>

All dimensions are given in mm.

**SMD** Surface-mount device

## Important notes

The following applies to all products named in this publication:

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2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
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